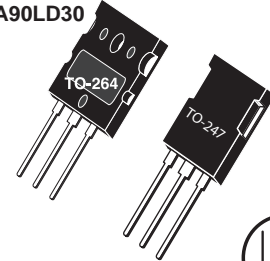
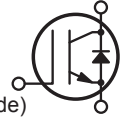



High Speed PT IGBT

POWER MOS 8® is a high speed Punch-Through switch-mode IGBT. Low E_{off} is achieved through leading technology silicon design and lifetime control processes. A reduced E_{off} - $V_{CE(ON)}$ tradeoff results in superior efficiency compared to other IGBT technologies. Low gate charge and a greatly reduced ratio of C_{res}/C_{ies} provide excellent noise immunity, short delay times and simple gate drive. The intrinsic chip gate resistance and capacitance of the poly-silicone gate structure help control di/dt during switching, resulting in low EMI, even when switching at high frequency.

APT64GA90LD30


 APT64GA90B2D30
 Combi (IGBT and Diode)


FEATURES

- Fast switching with low EMI
- Very Low E_{off} for maximum efficiency
- Ultra low C_{res} for improved noise immunity
- Low conduction loss
- Low gate charge
- Increased intrinsic gate resistance for low EMI
- RoHS compliant 

TYPICAL APPLICATIONS

- ZVS phase shifted and other full bridge
- Half bridge
- High power PFC boost
- Welding
- UPS, solar, and other inverters
- High frequency, high efficiency industrial

Absolute Maximum Ratings

Symbol	Parameter	Ratings	Unit
V_{CES}	Collector Emitter Voltage	900	V
I_{C1}	Continuous Collector Current @ $T_c = 25^\circ\text{C}$	117	A
I_{C2}	Continuous Collector Current @ $T_c = 100^\circ\text{C}$	64	
I_{CM}	Pulsed Collector Current ¹	193	
V_{GE}	Gate-Emitter Voltage ²	± 30	V
P_D	Total Power Dissipation @ $T_c = 25^\circ\text{C}$	500	W
SSOA	Switching Safe Operating Area @ $T_j = 150^\circ\text{C}$	193A @ 900V	
T_J, T_{STG}	Operating and Storage Junction Temperature Range	-55 to 150	°C
T_L	Lead Temperature for Soldering: 0.063" from Case for 10 Seconds	300	

Static Characteristics

 $T_J = 25^\circ\text{C}$ unless otherwise specified

Symbol	Parameter	Test Conditions	Min	Typ	Max	Unit
$V_{BR(CES)}$	Collector-Emitter Breakdown Voltage	$V_{GE} = 0V, I_C = 250\mu\text{A}$	900			V
$V_{CE(on)}$	Collector-Emitter On Voltage	$V_{GE} = 15V, I_C = 38A$ $T_J = 25^\circ\text{C}$ $T_J = 125^\circ\text{C}$		2.5 2.2	3.1	
$V_{GE(th)}$	Gate Emitter Threshold Voltage	$V_{GE} = V_{CE}, I_C = 1mA$	3	4.5	6	
I_{CES}	Zero Gate Voltage Collector Current	$V_{CE} = 900V, V_{GE} = 0V$ $T_J = 25^\circ\text{C}$ $T_J = 125^\circ\text{C}$			350 1500	μA
I_{GES}	Gate-Emitter Leakage Current	$V_{GS} = \pm 30V$			± 100	nA

Dynamic Characteristics
T_J = 25°C unless otherwise specified
APT64GA90L_B2D30

Symbol	Parameter	Test Conditions	Min	Typ	Max	Unit	
C _{ies}	Input Capacitance	Capacitance V _{GE} = 0V, V _{CE} = 25V f = 1MHz		3525		pF	
C _{oes}	Output Capacitance			318			
C _{res}	Reverse Transfer Capacitance			53			
Q _g ³	Total Gate Charge	Gate Charge V _{GE} = 15V V _{CE} = 450V I _C = 38A		162		nC	
Q _{ge}	Gate-Emitter Charge			26			
Q _{gc}	Gate- Collector Charge			64			
SSOA	Switching Safe Operating Area	T _J = 150°C, R _G = 4.7Ω ⁴ , V _{GE} = 15V, L = 100uH, V _{CE} = 900V	193			A	
t _{d(on)}	Turn-On Delay Time	Inductive Switching (25°C) V _{CC} = 600V V _{GE} = 15V I _C = 38A R _G = 4.7Ω ⁴ T _J = +25°C		18		ns	
t _r	Current Rise Time			26			
t _{d(off)}	Turn-Off Delay Time			131			
t _f	Current Fall Time			104			
E _{on2}	Turn-On Switching Energy	Inductive Switching (125°C) V _{CC} = 600V V _{GE} = 15V I _C = 38A R _G = 4.7Ω ⁴ T _J = +125°C		1192		μJ	
E _{off} ⁶	Turn-Off Switching Energy			1088			
t _{d(on)}	Turn-On Delay Time			17			ns
t _r	Current Rise Time			27			
t _{d(off)}	Turn-Off Delay Time		181				
t _f	Current Fall Time		171				
E _{on2}	Turn-On Switching Energy			1857		μJ	
E _{off} ⁶	Turn-Off Switching Energy			2311			

Thermal and Mechanical Characteristics

Symbol	Characteristic	Min	Typ	Max	Unit
R _{θJC}	Junction to Case Thermal Resistance (IGBT)	-	-	.25	°C/W
R _{θJC}	Junction to Case Thermal Resistance (Diode)			0.8	
W _T	Package Weight	-	6.1	-	g
Torque	Mounting Torque (TO-264 Package), 4-40 or M3 screw			10	in-lbf

1 Repetitive Rating: Pulse width and case temperature limited by maximum junction temperature.

2 Pulse test: Pulse Width < 380μs, duty cycle < 2%.

3 See Mil-Std-750 Method 3471.

4 R_G is external gate resistance, not including internal gate resistance or gate driver impedance. (MIC4452)

5 E_{on2} is the clamped inductive turn on energy that includes a commutating diode reverse recovery current in the IGBT turn on energy loss. A combi device is used for the clamping diode.

6 E_{off} is the clamped inductive turn-off energy measured in accordance with JEDEC standard JESD24-1.

Microsemi reserves the right to change, without notice, the specifications and information contained herein.

Typical Performance Curves

APT64GA90L_B2D30

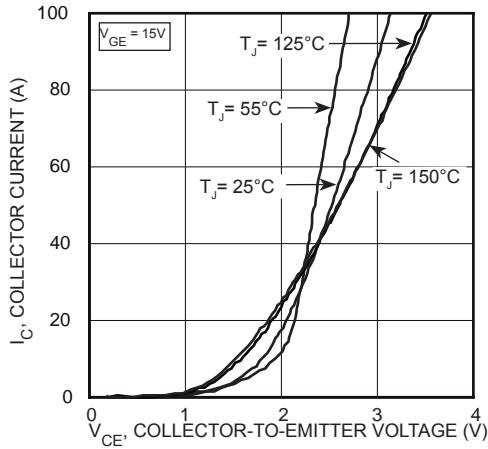


FIGURE 1, Output Characteristics ($T_J = 25^\circ\text{C}$)

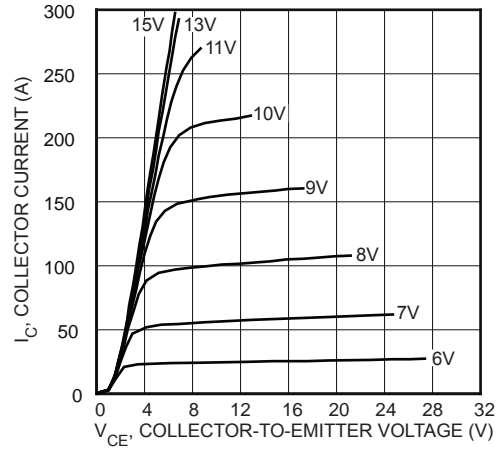


FIGURE 2, Output Characteristics ($T_J = 25^\circ\text{C}$)

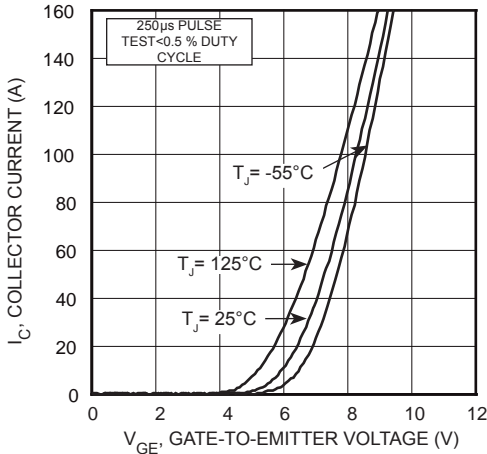


FIGURE 3, Transfer Characteristics

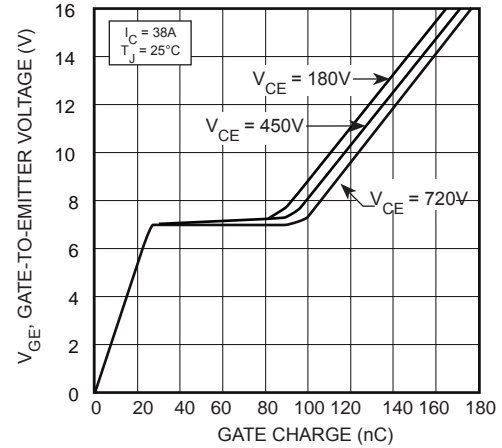


FIGURE 4, Gate charge

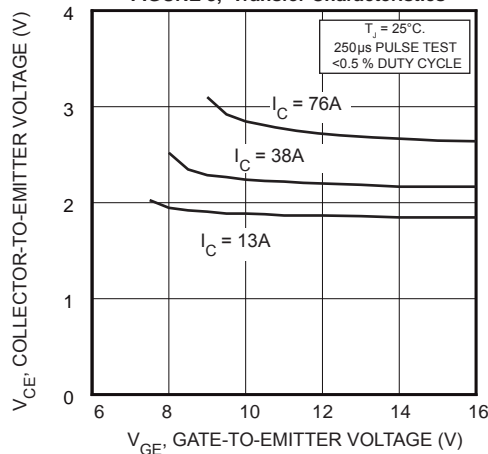


FIGURE 5, On State Voltage vs Gate-to-Emitter Voltage

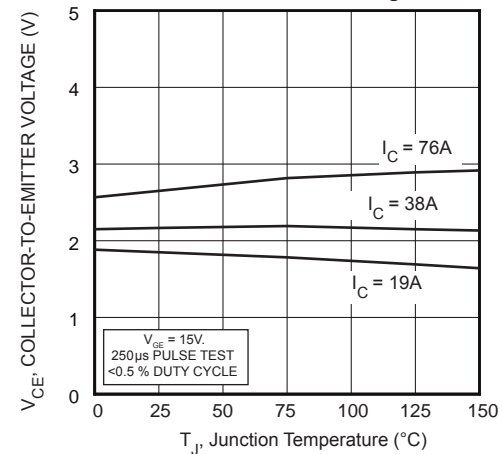


FIGURE 6, On State Voltage vs Junction Temperature

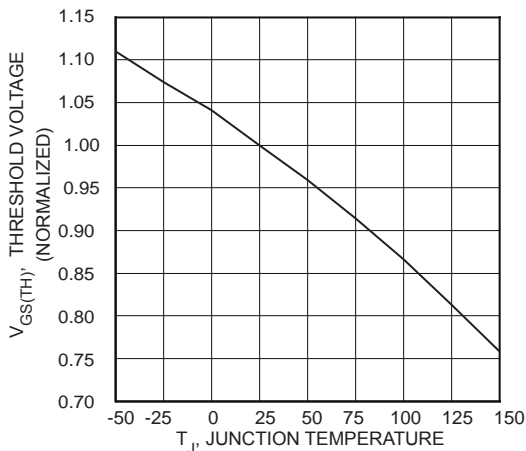


FIGURE 7, Threshold Voltage vs Junction Temperature

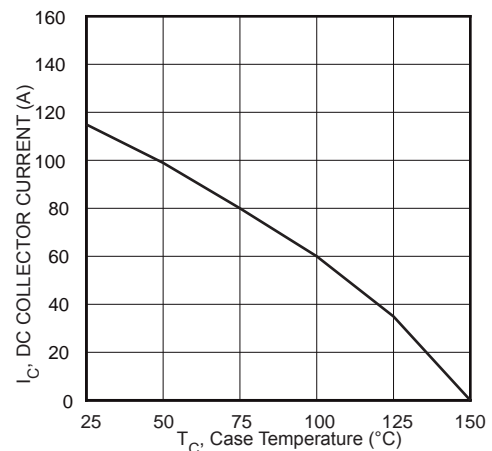


FIGURE 8, DC Collector Current vs Case Temperature

Typical Performance Curves

APT64GA90L_B2D30

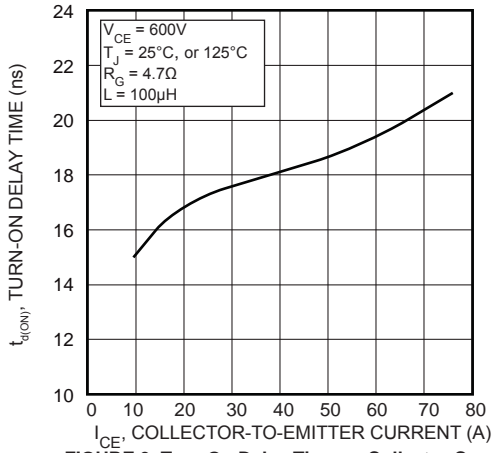


FIGURE 9, Turn-On Delay Time vs Collector Current

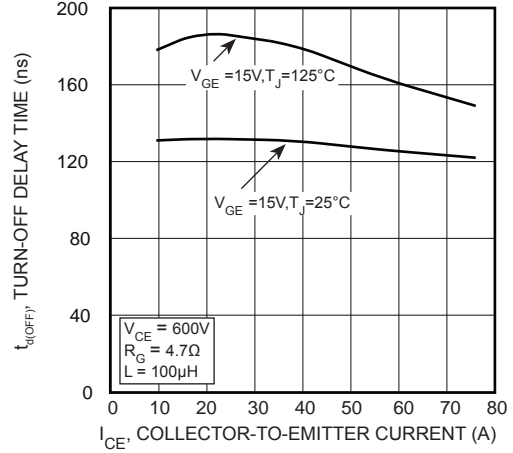


FIGURE 10, Turn-Off Delay Time vs Collector Current

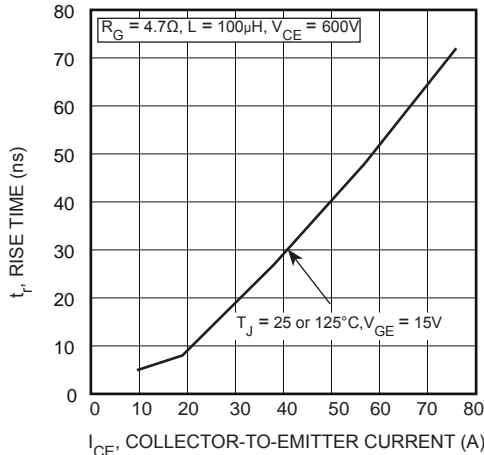


FIGURE 11, Current Rise Time vs Collector Current

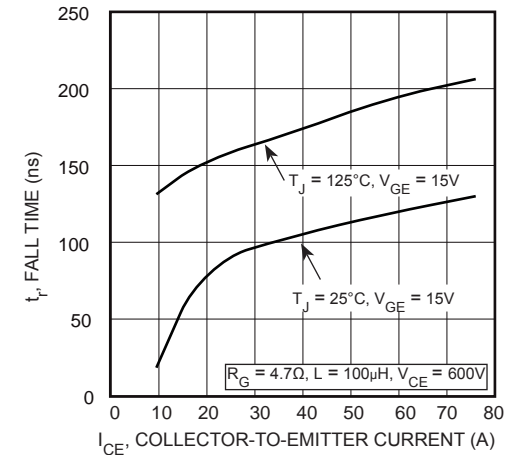


FIGURE 12, Current Fall Time vs Collector Current

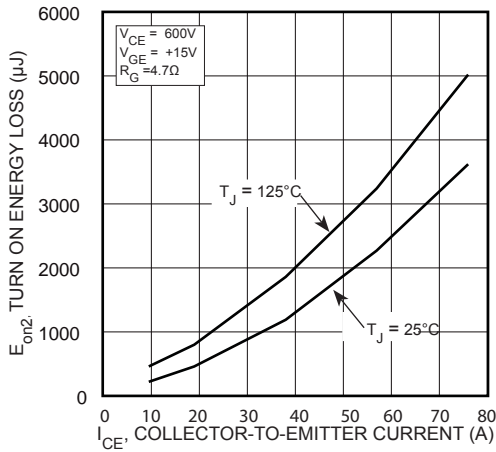


FIGURE 13, Turn-On Energy Loss vs Collector Current

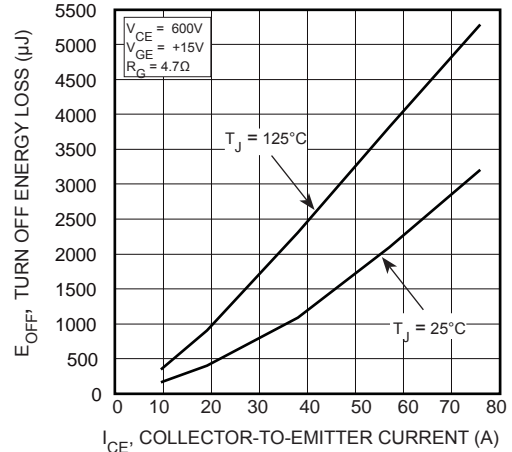


FIGURE 14, Turn-Off Energy Loss vs Collector Current

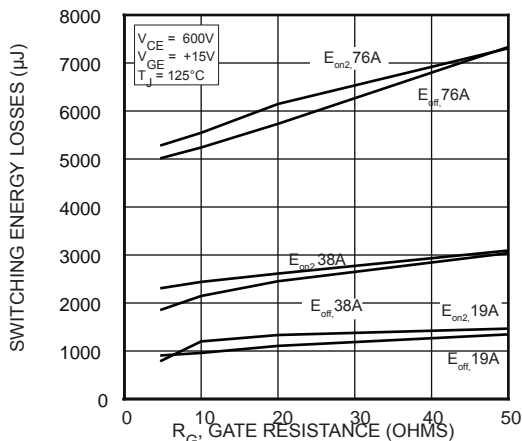


FIGURE 15, Switching Energy Losses vs Gate Resistance

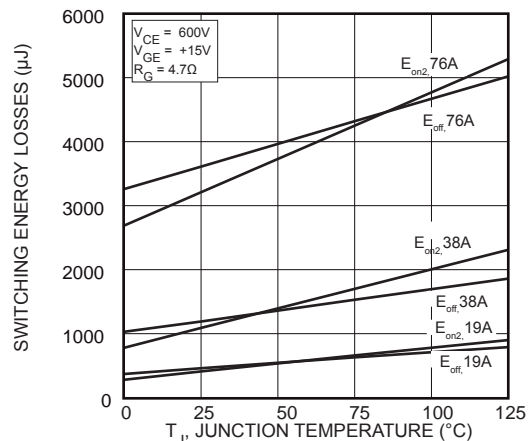


FIGURE 16, Switching Energy Losses vs Junction Temperature

Typical Performance Curves

APT64GA90L_B2D30

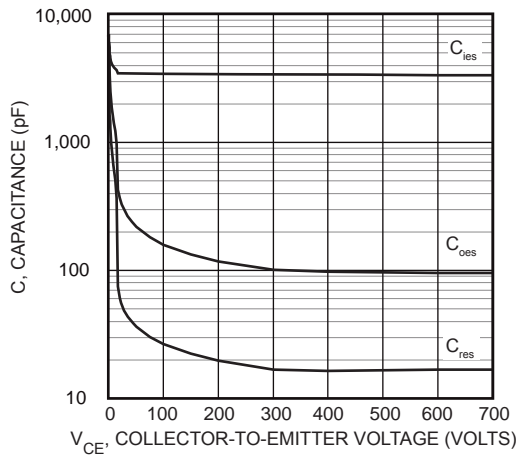


FIGURE 17, Capacitance vs Collector-To-Emitter Voltage

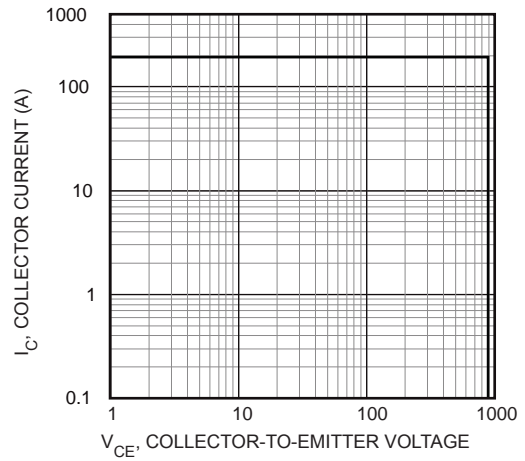


FIGURE 18, Minimum Switching Safe Operating Area

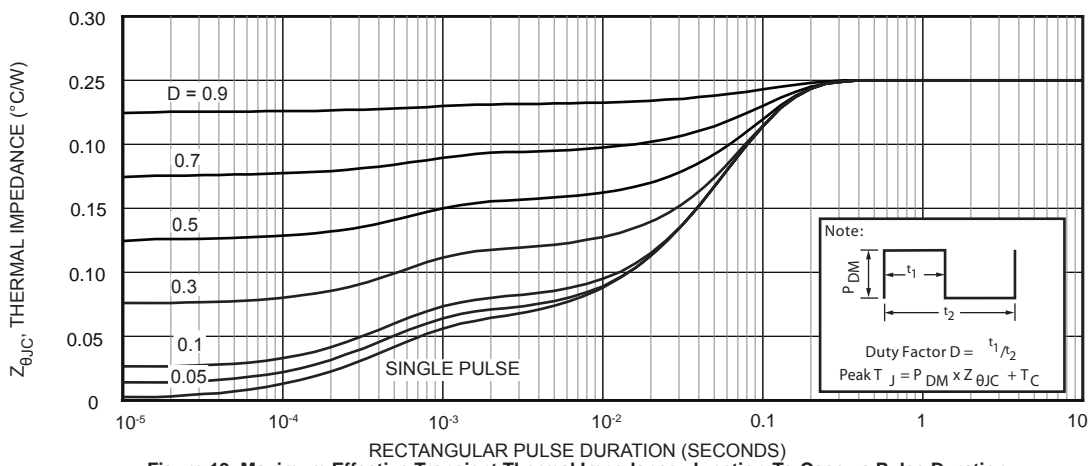


Figure 19, Maximum Effective Transient Thermal Impedance, Junction-To-Case vs Pulse Duration

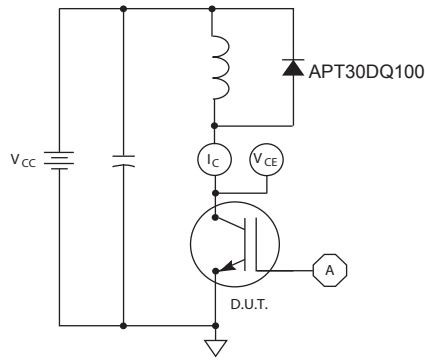


Figure 20, Inductive Switching Test Circuit

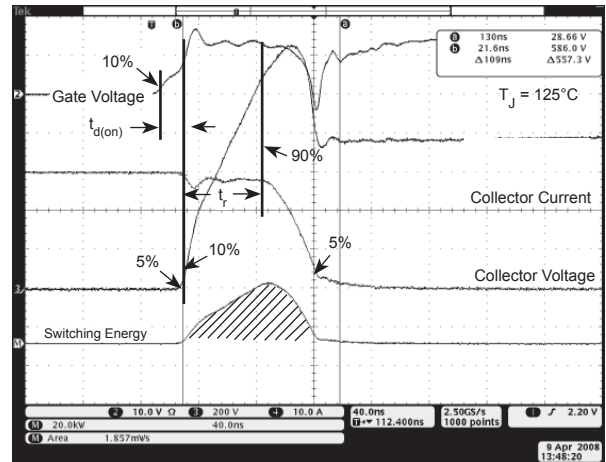


Figure 21, Turn-on Switching Waveforms and Definitions

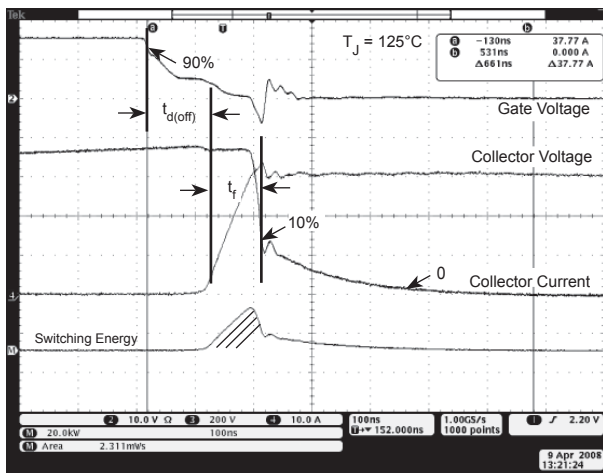


Figure 22, Turn-off Switching Waveforms and Definitions

ULTRAFAST SOFT RECOVERY RECTIFIER DIODE

MAXIMUM RATINGS

All Ratings: $T_C = 25^\circ\text{C}$ unless otherwise specified.

Symbol	Characteristic / Test Conditions	APT64GA90L_B2D30	Unit
$I_{F(AV)}$	Maximum Average Forward Current ($T_C = 102^\circ\text{C}$, Duty Cycle = 0.5)	30	Amps
$I_{F(RMS)}$	RMS Forward Current (Square wave, 50% duty)	43	
I_{FSM}	Non-Repetitive Forward Surge Current ($T_J = 45^\circ\text{C}$, 8.3 ms)	150	

STATIC ELECTRICAL CHARACTERISTICS

Symbol	Characteristic / Test Conditions	Min	Type	Max	Unit
V_F	Forward Voltage		$I_F = 30\text{A}$	2.5	Volts
			$I_F = 60\text{A}$	3.06	
			$I_F = 30\text{A}, T_J = 125^\circ\text{C}$	1.92	

DYNAMIC CHARACTERISTICS

Symbol	Characteristic	Test Conditions	Min	Typ	Max	Unit	
t_{rr}	Reverse Recovery Time	$I_F = 1\text{A}, di_F/dt = -100\text{A}/\mu\text{s}, V_R = 30\text{V}, T_J = 25^\circ\text{C}$	-	24	-	ns	
t_{rr}	Reverse Recovery Time	$I_F = 30\text{A}, di_F/dt = -200\text{A}/\mu\text{s}, V_R = 667\text{V}, T_C = 25^\circ\text{C}$	-	295	-	ns	
Q_{rr}	Reverse Recovery Charge		-	440	-		nC
I_{RRM}	Maximum Reverse Recovery Current		-	4	-		Amps
t_{rr}	Reverse Recovery Time	$I_F = 30\text{A}, di_F/dt = -200\text{A}/\mu\text{s}, V_R = 667\text{V}, T_C = 125^\circ\text{C}$	-	330	-	ns	
Q_{rr}	Reverse Recovery Charge		-	1550	-		nC
I_{RRM}	Maximum Reverse Recovery Current		-	8	-		Amps
t_{rr}	Reverse Recovery Time	$I_F = 30\text{A}, di_F/dt = -1000\text{A}/\mu\text{s}, V_R = 667\text{V}, T_C = 125^\circ\text{C}$	-	150	-	ns	
Q_{rr}	Reverse Recovery Charge		-	2250	-		nC
I_{RRM}	Maximum Reverse Recovery Current		-	25	-		Amps

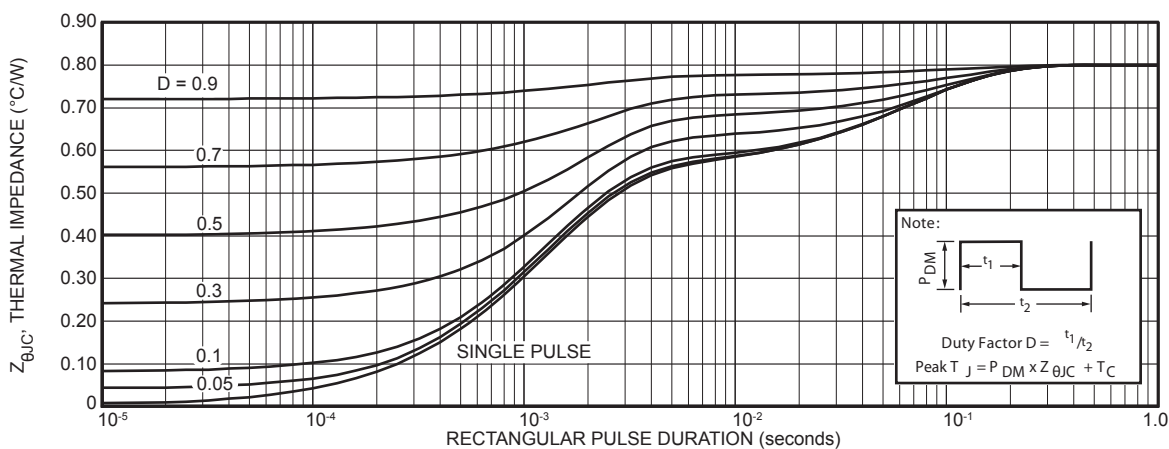


FIGURE 23. MAXIMUM EFFECTIVE TRANSIENT THERMAL IMPEDANCE, JUNCTION-TO-CASE vs. PULSE DURATION

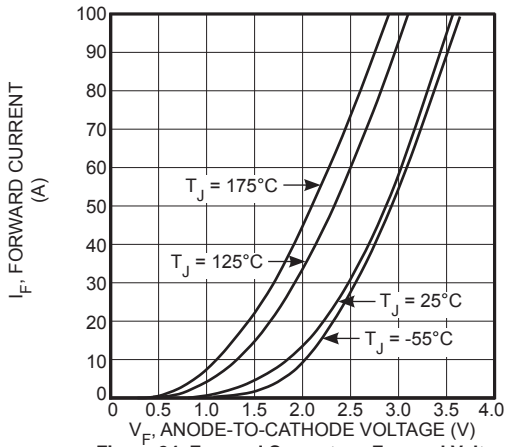


Figure 24. Forward Current vs. Forward Voltage

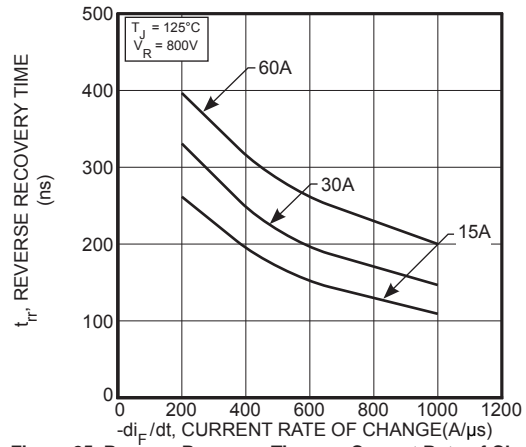


Figure 25. Reverse Recovery Time vs. Current Rate of Change

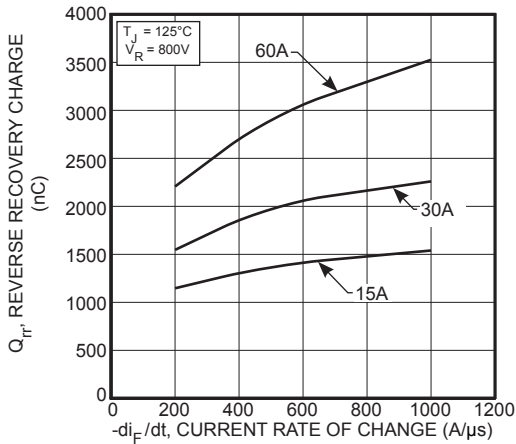


Figure 26. Reverse Recovery Charge vs. Current Rate of Change

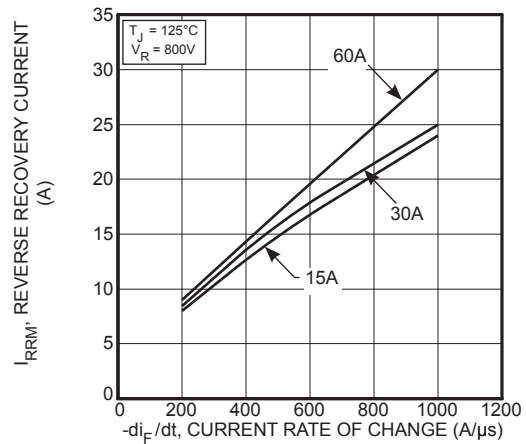


Figure 27. Reverse Recovery Current vs. Current Rate of Change

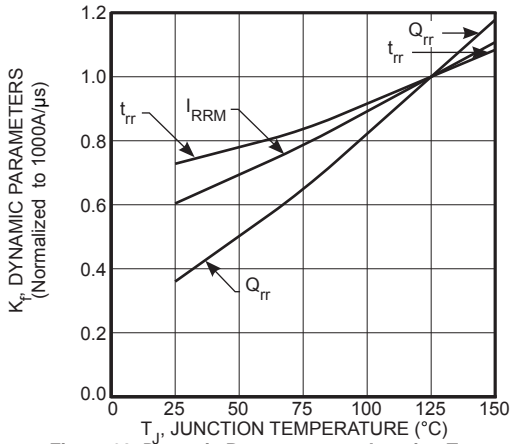


Figure 28. Dynamic Parameters vs. Junction Temperature

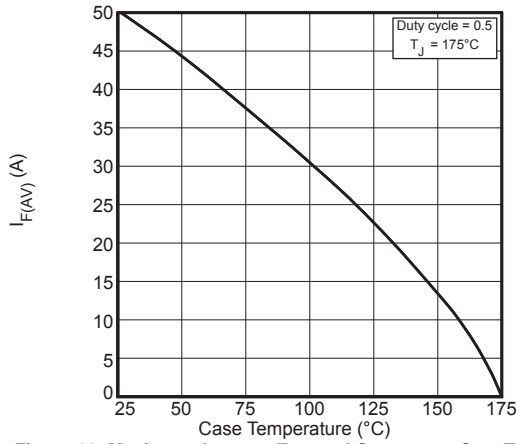


Figure 29. Maximum Average Forward Current vs. Case Temperature

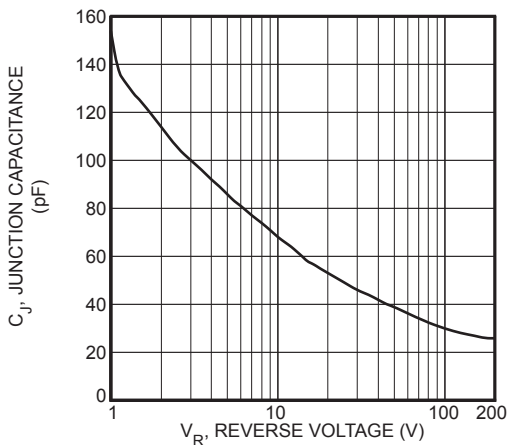


Figure 30. Junction Capacitance vs. Reverse Voltage

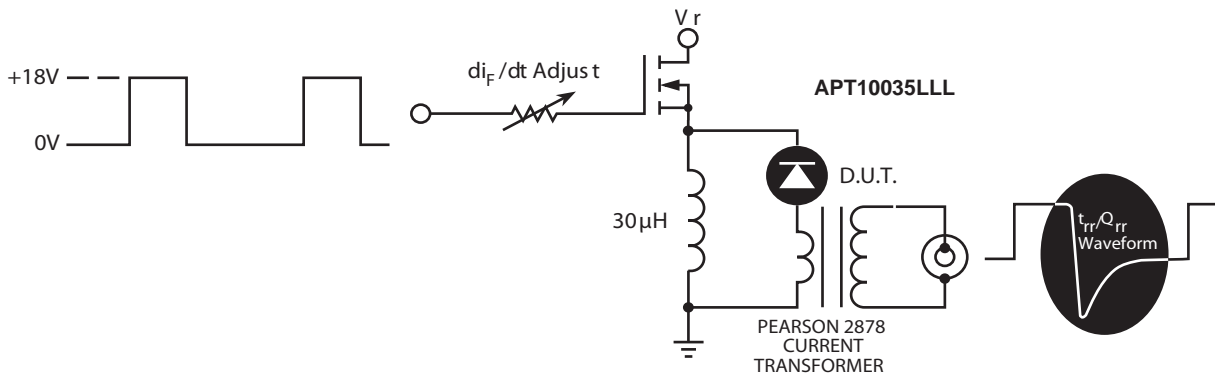


Figure 31. Diode Test Circuit

- 1 I_F - Forward Conduction Current
- 2 di_F/dt - Rate of Diode Current Change Through Zero Crossing.
- 3 I_{RRM} - Maximum Reverse Recovery Current
- 4 t_{rr} - Reverse Recovery Time measured from zero crossing where diode current goes from positive to negative, to the point at which the straight line through I_{RRM} and 0.25 I_{RRM} passes through zero.
- 5 Q_{rr} - Area Under the Curve Defined by I_{RRM} and t_{rr}.

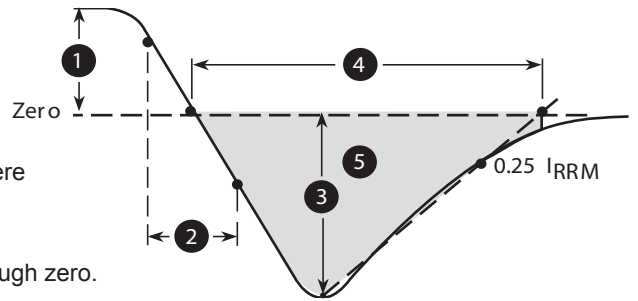
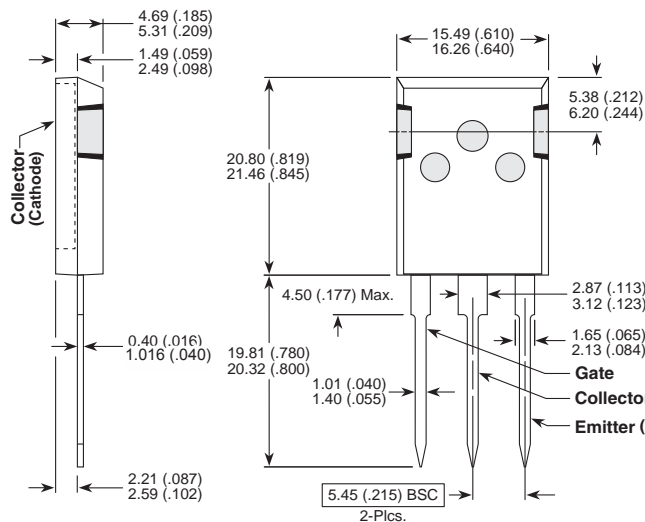


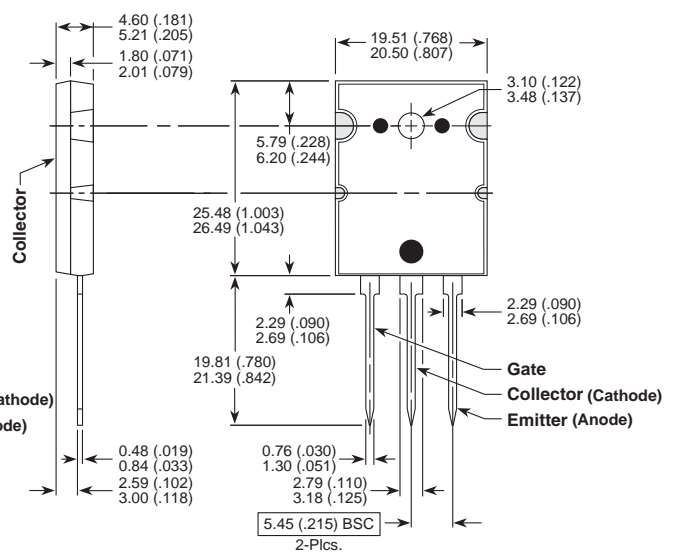
Figure 32. Diode Reverse Recovery Waveform Definition

T-MAX™ (B2) Package Outline



These dimensions are equal to the TO-247 without the mounting hole.
Dimensions in Millimeters and (Inches)

TO-264 (L) Package Outline



Dimensions in Millimeters and (Inches)